

# Mirror Mezz 15 x 11 OCP Connectors

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Footprint-compatible, hermaphroditic Mirror Mezz 15x11 OCP Connector lowers application costs with stackable mating that supports data speeds up to 56 Gbps per differential pair, for telecommunications, networking and other applications

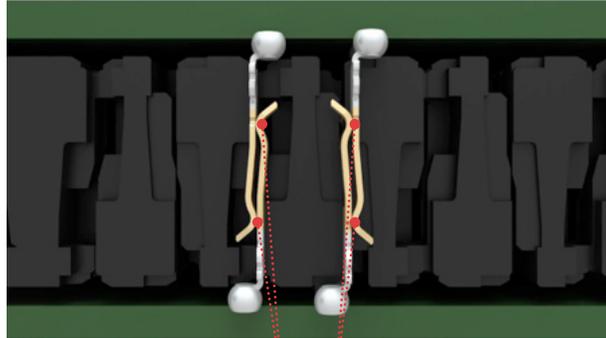
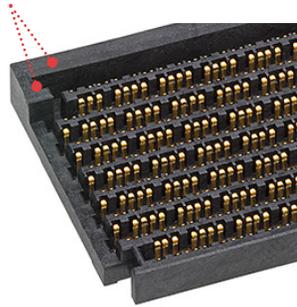


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## Features and Advantages

### Robust shrouded housing design

Encapsulates the pin field, protecting the pins and offering blind-mate guidance to eliminate any possibility of mis-mating

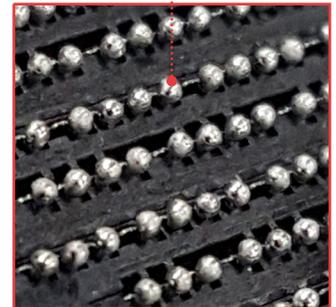


### Contact beam structure of a mated combination

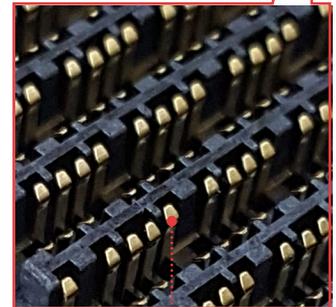
Prevents vibrations and terminal lift to ensure a constant 2-points of contact for electrical reliability. Beam geometry offers reliable normal force for harsh environments and 1.50mm of nominal contact wipe to ensure sufficient engagement

### Stitched BGA design

Offers greater cost savings than insert-molded BGA attachments. Stitched contact structure reduces lead times and the connector design simplifies product matrix



Top-side perspectives of Mirror Mezz Connector

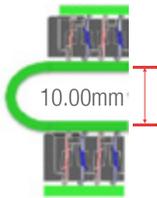


### Intricate terminal structure design

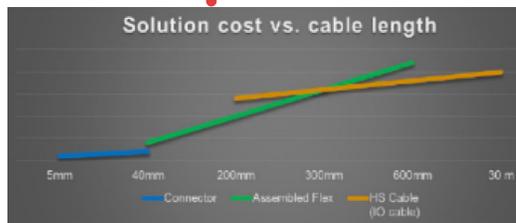
Provides numerous mechanical strengths while also benefiting from cutting-edge electrical features, for some of the fastest speeds in the industry

### Flex cable links

- Offer cost savings and excellent SI with controlled channels and pinned grounds
- Enable relaxed tolerancing for offsets between boards and flexible architectures

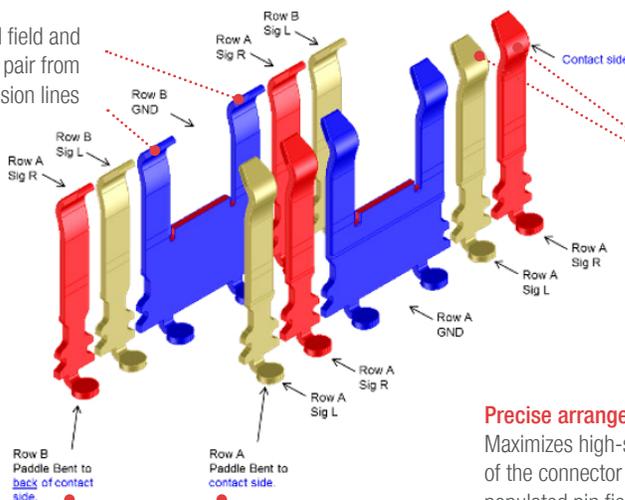


Using two 5.00mm stack height Mirror Mezz Connectors with 10.00mm flex provides 20.00 to 120.00mm stack heights



### Wide ground pins

Balance the electrical field and shield the differential pair from surrounding transmission lines



### 2 electrically tuned signal contacts

Cleanly transmit high-speed signals for maximum signal integrity surrounding transmission lines

### Precise arranged combination of signals and grounds

Maximizes high-speed performance and clean routing out of the connector footprint, with precisely arranged and populated pin field transmission lines

### Different paddle-to-contact bend direction between the rows

Minimizes the cross-talk between rows

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## Markets and Applications

### Data/Computing

- Servers
- Networking
- Storage

### Telecommunications/Networking

- Infrastructure
- Networking



Networking



Storage

## Specifications

### REFERENCE INFORMATION

Packaging: Tape and Reel  
Mates With: 2.50 and 5.50mm height  
connectors can self- or cross-mate  
Designed In: Millimeters  
RoHS: Yes  
Halogen Free: Yes  
Glow Wire Compliant: NA

### ELECTRICAL

Voltage (max.): 30V AC  
Current (max.): 1.0A per contact  
Low Level Contact Resistance (max. initial):  
30 milliohm for 5mm stack height  
Dielectric Withstanding Voltage: 500V DC  
Insulation Resistance: 1000 Megohms  
Impedance: 90 Ohms

### MECHANICAL

Average Mating Force (max.): 0.35N per pin  
Unmating Force (min.): 0.045N per pin  
Contact Normal Force (min.): 0.2N per pin  
Durability (max.): 100 cycles

### PHYSICAL

Housing: High Temperature Thermoplastic, UL94-V0  
Contact: High Performance Copper Alloy  
Plating: Selective Gold  
Contact Area — 0.76 micron Gold (Au)  
Solder Tail Area — 2.54 micron Tin (Sn)  
Underplating — 1.27 micron Nickel (Ni)  
Operating Temperature: -55 to +105°C

[www.molex.com/link/mirormezz.html](http://www.molex.com/link/mirormezz.html)

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